Ì,

PTO/SB/08A (10-01)
Approved for use through 10/31/2002. OMB 0651-0031

U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE
Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB

-	OTHER DE LIBERTY							
	Substitut	e for form 1449A/P	го		Complete if Known			
		DIATION			Application Number			
	INFC	RMATION	וטו:	SCLOSURE	Filing Date			
	STA	TEMENT B	BY A	APPLICANT	First Named Inventor	RONALD GENE FILIPPI		
					Art Unit			
		(use as many she	ets as	s necessary)	Examiner Name			
	Sheet	1	of	2	Attorney Docket Number	YOR920040086US1 (163-32)		

-	U.S. PATENT DOCUMENTS								
Examiner Initials	Cite No. 1 Number - Kind Code ² (if kr		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear				
		us- 10/726,140		HABIB HICHRI et al.					
		US-							
		US-							
		US-	·						
		US-							
		US-							
		US-							
		US-							
		US-							
		US-							
		US-			ALL PARTY AND ADDRESS OF THE PARTY AND ADDRESS				
		US-							
		US-							
		US-							
		US-							
		us-							
		US-							
		US-							
		US-							
		US-							

	FOREIGN PATENT DOCUMENTS										
Examiner Initials	Cite No.1	Foreign Patent Document Country Code 3 - Number 4 - Kind Code 5 (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	Т6					
											
						-					
						-					

Examiner	Date	
Signature	 Considered	

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.

^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

1 Applicant's unique citation designation number (optional). 2 See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. 3 Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). 4 For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. 5 Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. 6 Applicant is to place a check mark here if Enclish tensures. Translation is attracted. English language Translation is attached.

PTO/SB/08B (10-01)
Approved for use through 10/31/2002. OMB 0651-0031
U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE
Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

CONTROL HOLL						
Substitute f	or form 1449B/PTO			Complete if Known		
MEGE	ANATION!		OL OOUDE	Application Number		
INFOR	KIVIA HON!	DIS	CLOSURE	Filing Date		
STAT	EMENT RY	γ Δ	PPLICANT	First Named Inventor	RONALD GENE FILIPPI	
ואוט		. ^	LIOAN	Group Art Unit		
	(use as many she	ets a	s necessary)	Examiner Name		
Sheet	2	of	2	Attorney Docket Number	YOR920040086US1 (163-32)	

Examiner	Cite	OTHER PRIOR ART NON PATENT LITERATURE DOCUMENTS Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue	T,
Initials*	No. ¹	number(s) publisher city and/or country where published HANCE H. HUSTON and C. PATRICK CLARKE; "Reliability Defect Detection and Screening during Processing - Theory and Implementation"; IEEE/IRPS; Jan.1992; pp. 268-275	+
		R. G. FILIPPI et al.; "Thermal Cycle Reliability of Stacked Via Structures with Copper Metallization and an Organic Low-K Dielectric"; sent in Oct. 2003 to International Reliability Physics Symposium committee for later publishing; 4 pages (including 2004 IRPS Submission Cover Page and article)	
		R. G. FILIPPI et al.; "Thermal Cycle Reliability of Stacked Via Structures with Copper Metallization and an Organic Low-K Dielectric"; IBM Hopewell Junction, NY Yorktown Heights, NY, Essex Junction, VT; February 20, 2004; 7 pages	
			_
			_
			_
			_
Examine		Date	

Examiner	Date	
Signature	Considered	

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.

^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). 2 Applicant is to place a check mark here if English language Translation is attached.